Please Note PCN-OPT-1275-2023 Valid From 01-Sep-23 (click here)



DESCRIPTION

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Vishay Semiconductors

High Speed Infrared Emitting Diode, 890 nm, Surface Emitter Technology



TSHF5210 is an infrared, 890 nm emitting diode based on surface emitter chip technology with high radiant power and

high speed, molded in a clear, untinted plastic package.

FEATURES

- · Package type: leaded
- Package form: T-1¾
- Dimensions (in mm): Ø 5
- Leads with stand-off
- Peak wavelength: $\lambda_p = 890 \text{ nm}$
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\varphi = \pm 8^{\circ}$
- Low forward voltage
- Suitable for high pulse current operation
- Good spectral matching with Si photodetectors
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Infrared high speed remote control and free air data transmission systems with high modulation frequencies or high data transmission rate requirements
- Transmission systems according to IrDA requirements and for carrier frequency based systems (e.g. ASK/FSK coded, 450 kHz or 1.3 MHz)

PRODUCT SUMMARY COMPONENT Ie (mW/sr) φ (°) λp (nm) tr (ns) TSHF5210 327 ± 8 890 10

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION							
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM				
TSHF5210	Bulk	MOQ: 4000 pcs, 4000 pcs/bulk	T-1¾				

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT			
Reverse voltage		V _R	5	V			
Forward current		١ _F	100	mA			
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I _{FM}	200	mA			
Surge forward current	t _p = 100 μs	I _{FSM}	1	A			
Power dissipation		Pv	170	mW			
Junction temperature		Тj	100	°C			
Ambient temperature range		T _{amb}	-40 to +85	°C			
Storage temperature range		T _{stg}	-40 to +100	°C			
Soldering temperature	$t \le 5$ s, 2 mm from case	T _{sd}	260	°C			
Thermal resistance junction to ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	230	K/W			

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COMPLIANT

HALOGEN

FREE

GREEN (5-2008)

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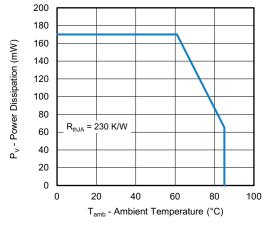


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

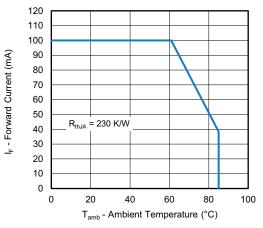


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT		
Forward voltage	I _F = 100 mA, t _p = 20 ms	V _F	-	1.5	1.7	V		
	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	V _F	-	3	-	V		
Temperature coefficient of V_F	I _F = 100 mA, t _p = 20 ms	TK _{VF}	-	-1.3	-	mV/K		
Reverse current		I _R	Not designed for reverse operation			μA		
Junction capacitance	$V_R = 0 V, f = 1 MHz, E = 0 mW/cm^2$	Cj	-	55	-	pF		
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	150	327	450	mW/sr		
	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	l _e	-	2700	-	mW/sr		
Radiant power	I _F = 100 mA, t _p = 20 ms	фе	-	53	-	mW		
Temperature coefficient of ϕ_{e}	I _F = 100 mA	ΤKφ _e	-	-0.3	-	%/K		
Angle of half intensity		φ	-	± 8	-	0		
Peak wavelength	I _F = 100 mA	λρ	-	890	-	nm		
Spectral bandwidth	I _F = 100 mA	Δλ	-	40	-	nm		
Temperature coefficient of λ_p	I _F = 100 mA	ΤΚλ _ρ	-	0.3	-	nm/K		
Rise time	I _F = 100 mA	t _r	-	10	-	ns		
Fall time	I _F = 100 mA	t _f	-	10	-	ns		

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BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

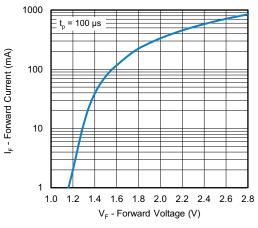


Fig. 3 - Forward Current vs. Forward Voltage

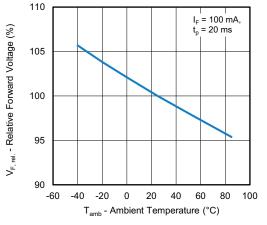


Fig. 4 - Relative Forward Voltage vs Ambient Temperature

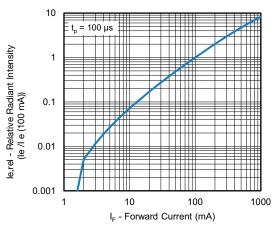


Fig. 5 - Relative Radiant Intensity vs. Forward Current

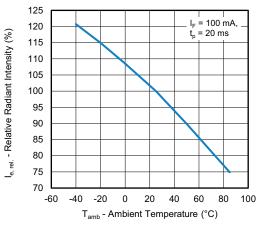


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

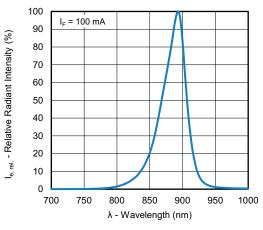


Fig. 7 - Relative Radiant Intensity vs. Wavelength

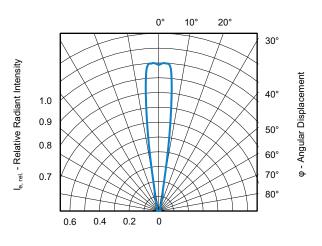


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

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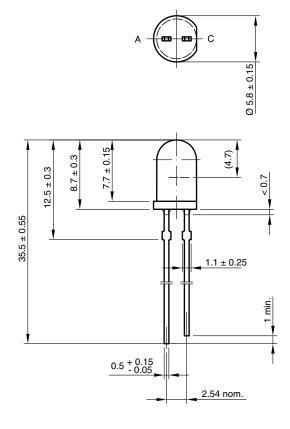


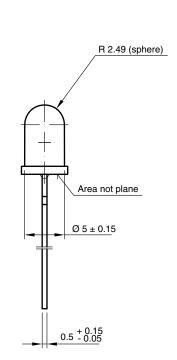
TSHF5210

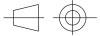
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PACKAGE DIMENSIONS in millimeters







technical drawings according to DIN specifications

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